



Product Change Notification: DSNO-01SOPR415

Date:

03-Nov-2025

Product Category:

Ethernet Phys

Notification Subject:

CCB 7393.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for KSZ8081RNACA, KSZ8081RNACA-TR, KSZ8081RNAIA-TR, KSZ8081RNDCA-TR, KSZ8081RNDIA-TR, KSZ8091RNACA-TR, KSZ8091RNAIA-TR, KSZ8091RNDCA-TR, KSZ8091RNDIA-TR, SPNY801142-TR, SPNY801143-TR, SPNY801147-TR, SPNZ801128-TR, SPNZ801143 and SPNZ801143-TR catalog part numbers (CPN) available in 24L VQFN (4x4x0.9mm) package.

Affected CPNs:

[DSNO-01SOPR415_Affected_CPN_11032025.pdf](#)

[DSNO-01SOPR415_Affected_CPN_11032025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for KSZ8081RNACA, KSZ8081RNACA-TR, KSZ8081RNAIA-TR, KSZ8081RNDCA-TR, KSZ8081RNDIA-TR, KSZ8091RNACA-TR, KSZ8091RNAIA-TR, KSZ8091RNDCA-TR, KSZ8091RNDIA-TR, SPNY801142-TR, SPNY801143-TR, SPNY801147-TR, SPNZ801128-TR, SPNZ801143 and SPNZ801143-TR catalog part numbers (CPN) available in 24L VQFN (4x4x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519	QMI519	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	A194	A194	No

Note: The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #[CENO-16EGCZ399](#).

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 23 January 2026 (date code: 2604)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	November 2025					>	January 2026				
Work Week	45	46	47	48	49		01	02	03	04	05
Qual Report Availability	X										
Final PCN Issue Date	X										
Estimated Implementation Date										X	

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: November 03, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-01SOPR415_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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